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AMD Xilinx - XC2S15-5TQ144I Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	96
Number of Logic Elements/Cells	432
Total RAM Bits	16384
Number of I/O	86
Number of Gates	15000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2s15-5tq144i

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Spartan-II FPGA Family: Introduction and Ordering Information

Product Specification

Introduction

The Spartan[®]-II Field-Programmable Gate Array family gives users high performance, abundant logic resources, and a rich feature set, all at an exceptionally low price. The six-member family offers densities ranging from 15,000 to 200,000 system gates, as shown in Table 1. System performance is supported up to 200 MHz. Features include block RAM (to 56K bits), distributed RAM (to 75,264 bits), 16 selectable I/O standards, and four DLLs. Fast, predictable interconnect means that successive design iterations continue to meet timing requirements.

The Spartan-II family is a superior alternative to mask-programmed ASICs. The FPGA avoids the initial cost, lengthy development cycles, and inherent risk of conventional ASICs. Also, FPGA programmability permits design upgrades in the field with no hardware replacement necessary (impossible with ASICs).

Features

- Second generation ASIC replacement technology
 - Densities as high as 5,292 logic cells with up to 200,000 system gates
 - Streamlined features based on Virtex[®] FPGA architecture
 - Unlimited reprogrammability
 - Very low cost
 - Cost-effective 0.18 micron process

- System level features
 - SelectRAM[™] hierarchical memory:
 - · 16 bits/LUT distributed RAM
 - Configurable 4K bit block RAM
 - Fast interfaces to external RAM
 - Fully PCI compliant
 - Low-power segmented routing architecture
 - Full readback ability for verification/observability
 - Dedicated carry logic for high-speed arithmetic
 - Efficient multiplier support
 - Cascade chain for wide-input functions
 - Abundant registers/latches with enable, set, reset
 - Four dedicated DLLs for advanced clock control
 - Four primary low-skew global clock distribution nets
 - IEEE 1149.1 compatible boundary scan logic
- Versatile I/O and packaging
 - Pb-free package options
 - Low-cost packages available in all densities
 - Family footprint compatibility in common packages
 - 16 high-performance interface standards
 - Hot swap Compact PCI friendly
 - Zero hold time simplifies system timing
- Core logic powered at 2.5V and I/Os powered at 1.5V, 2.5V, or 3.3V
- Fully supported by powerful Xilinx[®] ISE[®] development system
 - Fully automatic mapping, placement, and routing

Table 1: Spartan-II FPGA Family Members								
Device	Logic Cells	System Gates (Logic and RAM)	CLB Array (R x C)	Total CLBs	Maximum Available User I/O ⁽¹⁾	Total Distributed RAM Bits	Total Block RAM Bits	
XC2S15	432	15,000	8 x 12	96	86	6,144	16K	
XC2S30	972	30,000	12 x 18	216	92	13,824	24K	
XC2S50	1,728	50,000	16 x 24	384	176	24,576	32K	
XC2S100	2,700	100,000	20 x 30	600	176	38,400	40K	
XC2S150	3,888	150,000	24 x 36	864	260	55,296	48K	
XC2S200	5,292	200,000	28 x 42	1,176	284	75,264	56K	

Notes:

1. All user I/O counts do not include the four global clock/user input pins. See details in Table 2, page 4.

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General Overview

The Spartan-II family of FPGAs have a regular, flexible, programmable architecture of Configurable Logic Blocks (CLBs), surrounded by a perimeter of programmable Input/Output Blocks (IOBs). There are four Delay-Locked Loops (DLLs), one at each corner of the die. Two columns of block RAM lie on opposite sides of the die, between the CLBs and the IOB columns. These functional elements are interconnected by a powerful hierarchy of versatile routing channels (see Figure 1).

Spartan-II FPGAs are customized by loading configuration data into internal static memory cells. Unlimited reprogramming cycles are possible with this approach. Stored values in these cells determine logic functions and interconnections implemented in the FPGA. Configuration data can be read from an external serial PROM (master serial mode), or written into the FPGA in slave serial, slave parallel, or Boundary Scan modes.

Spartan-II FPGAs are typically used in high-volume applications where the versatility of a fast programmable solution adds benefits. Spartan-II FPGAs are ideal for shortening product development cycles while offering a cost-effective solution for high volume production.

Spartan-II FPGAs achieve high-performance, low-cost operation through advanced architecture and semiconductor technology. Spartan-II devices provide system clock rates up to 200 MHz. In addition to the conventional benefits of high-volume programmable logic solutions, Spartan-II FPGAs also offer on-chip synchronous single-port and dual-port RAM (block and distributed form), DLL clock drivers, programmable set and reset on all flip-flops, fast carry logic, and many other features.







Figure 4: Spartan-II CLB Slice (two identical slices in each CLB)

Storage Elements

Storage elements in the Spartan-II FPGA slice can be configured either as edge-triggered D-type flip-flops or as level-sensitive latches. The D inputs can be driven either by function generators within the slice or directly from slice inputs, bypassing the function generators.

In addition to Clock and Clock Enable signals, each slice has synchronous set and reset signals (SR and BY). SR forces a storage element into the initialization state specified for it in the configuration. BY forces it into the opposite state. Alternatively, these signals may be configured to operate asynchronously.

All control signals are independently invertible, and are shared by the two flip-flops within the slice.

Additional Logic

The F5 multiplexer in each slice combines the function generator outputs. This combination provides either a function generator that can implement any 5-input function, a 4:1 multiplexer, or selected functions of up to nine inputs.



Notes: (referring to waveform above:)

1. Before configuration can begin, V_{CCINT} must be greater than 1.6V and V_{CCO} Bank 2 must be greater than 1.0V.

Figure 12: Configuration Timing on Power-Up

Clearing Configuration Memory

The device indicates that clearing the configuration memory is in progress by driving INIT Low. At this time, the user can delay configuration by holding either PROGRAM or INIT Low, which causes the device to remain in the memory clearing phase. Note that the bidirectional INIT line is driving a Low logic level during memory clearing. To avoid contention, use an open-drain driver to keep INIT Low.

With no delay in force, the device indicates that the memory is completely clear by driving INIT High. The FPGA samples its mode pins on this Low-to-High transition.

Loading Configuration Data

Once INIT is High, the user can begin loading configuration data frames into the device. The details of loading the configuration data are discussed in the sections treating the configuration modes individually. The sequence of operations necessary to load configuration data using the serial modes is shown in Figure 14. Loading data using the Slave Parallel mode is shown in Figure 19, page 25.

CRC Error Checking

During the loading of configuration data, a CRC value embedded in the configuration file is checked against a CRC value calculated within the FPGA. If the CRC values do not match, the FPGA drives INIT Low to indicate that a frame error has occurred and configuration is aborted.

To reconfigure the device, the PROGRAM pin should be asserted to reset the configuration logic. Recycling power also resets the FPGA for configuration. See "Clearing Configuration Memory".

Start-up

The start-up sequence oversees the transition of the FPGA from the configuration state to full user operation. A match of CRC values, indicating a successful loading of the configuration data, initiates the sequence.

During start-up, the device performs four operations:

- 1. The assertion of DONE. The failure of DONE to go High may indicate the unsuccessful loading of configuration data.
- 2. The release of the Global Three State net. This activates I/Os to which signals are assigned. The remaining I/Os stay in a high-impedance state with internal weak pull-down resistors present.
- 3. Negates Global Set Reset (GSR). This allows all flip-flops to change state.
- 4. The assertion of Global Write Enable (GWE). This allows all RAMs and flip-flops to change state.



DS001_16_032300

Symbol		Description		Units
T _{DCC}		DIN setup	5	ns, min
T _{CCD}		DIN hold	0	ns, min
т _{ссо}		DOUT	12	ns, max
т _{ссн}	COLK	High time	5	ns, min
T _{CCL}		Low time	5	ns, min
F _{CC}		Maximum frequency	66	MHz, max

Figure 16: Slave Serial Mode Timing

Master Serial Mode

In Master Serial mode, the CCLK output of the FPGA drives a Xilinx PROM which feeds a serial stream of configuration data to the FPGA's DIN input. Figure 15 shows a Master Serial FPGA configuring a Slave Serial FPGA from a PROM. A Spartan-II device in Master Serial mode should be connected as shown for the device on the left side. Master Serial mode is selected by a <00x> on the mode pins (M0, M1, M2). The PROM RESET pin is driven by INIT, and CE input is driven by DONE. The interface is identical to the slave serial mode except that an oscillator internal to the FPGA is used to generate the configuration clock (CCLK). Any of a number of different frequencies ranging from 4 to 60 MHz can be set using the ConfigRate option in the Xilinx software. On power-up, while the first 60 bytes of the configuration data are being loaded, the CCLK frequency is always 2.5 MHz. This frequency is used until the ConfigRate bits, part of the configuration file, have been loaded into the FPGA, at which point, the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz. The frequency of the CCLK signal created by the internal oscillator has a variance of +45%, -30% from the specified value.

Figure 17 shows the timing for Master Serial configuration. The FPGA accepts one bit of configuration data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge.



Figure 17: Master Serial Mode Timing

Slave Parallel Mode

The Slave Parallel mode is the fastest configuration option. Byte-wide data is written into the FPGA. A BUSY flag is provided for controlling the flow of data at a clock frequency F_{CCNH} above 50 MHz.

Figure 18, page 24 shows the connections for two Spartan-II devices using the Slave Parallel mode. Slave Parallel mode is selected by a <011> on the mode pins (M0, M1, M2).

If a configuration file of the format .bit, .rbt, or non-swapped HEX is used for parallel programming, then the most significant bit (i.e. the left-most bit of each configuration byte, as displayed in a text editor) must be routed to the D0 input on the FPGA. The agent controlling configuration is not shown. Typically, a processor, a microcontroller, or CPLD controls the Slave Parallel interface. The controlling agent provides byte-wide configuration data, CCLK, a Chip Select (\overline{CS}) signal and a Write signal (WRITE). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

After configuration, the pins of the Slave Parallel port (D0-D7) can be used as additional user I/O. Alternatively, the port may be retained to permit high-speed 8-bit readback. Then data can be read by de-asserting WRITE. See "Readback," page 25.

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Figure 20: Slave Parallel Write Timing



Figure 21: Slave Parallel Write Abort Waveforms

BUFGDLL Pin Descriptions

Use the BUFGDLL macro as the simplest way to provide zero propagation delay for a high-fanout on-chip clock from an external input. This macro uses the IBUFG, CLKDLL and BUFG primitives to implement the most basic DLL application as shown in Figure 25.



Figure 25: BUFGDLL Block Diagram

This macro does not provide access to the advanced clock domain controls or to the clock multiplication or clock division features of the DLL. This macro also does not provide access to the RST or LOCKED pins of the DLL. For access to these features, a designer must use the DLL primitives described in the following sections.

Source Clock Input — I

The I pin provides the user source clock, the clock signal on which the DLL operates, to the BUFGDLL. For the BUFGDLL macro the source clock frequency must fall in the low frequency range as specified in the data sheet. The BUFGDLL requires an external signal source clock. Therefore, only an external input port can source the signal that drives the BUFGDLL I pin.

Clock Output — O

The clock output pin O represents a delay-compensated version of the source clock (I) signal. This signal, sourced by a global clock buffer BUFG primitive, takes advantage of the dedicated global clock routing resources of the device.

The output clock has a 50/50 duty cycle unless you deactivate the duty cycle correction property.

CLKDLL Primitive Pin Descriptions

The library CLKDLL primitives provide access to the complete set of DLL features needed when implementing more complex applications with the DLL.

Source Clock Input — CLKIN

The CLKIN pin provides the user source clock (the clock signal on which the DLL operates) to the DLL. The CLKIN frequency must fall in the ranges specified in the data sheet. A global clock buffer (BUFG) driven from another CLKDLL

or one of the global clock input buffers (IBUFG) on the same edge of the device (top or bottom) must source this clock signal.

Feedback Clock Input — CLKFB

The DLL requires a reference or feedback signal to provide the delay-compensated output. Connect only the CLK0 or CLK2X DLL outputs to the feedback clock input (CLKFB) pin to provide the necessary feedback to the DLL. Either a global clock buffer (BUFG) or one of the global clock input buffers (IBUFG) on the same edge of the device (top or bottom) must source this clock signal.

If an IBUFG sources the CLKFB pin, the following special rules apply.

- 1. An external input port must source the signal that drives the IBUFG I pin.
- The CLK2X output must feed back to the device if both the CLK0 and CLK2X outputs are driving off chip devices.
- 3. That signal must directly drive only OBUFs and nothing else.

These rules enable the software to determine which DLL clock output sources the CLKFB pin.

Reset Input — RST

When the reset pin RST activates, the LOCKED signal deactivates within four source clock cycles. The RST pin, active High, must either connect to a dynamic signal or be tied to ground. As the DLL delay taps reset to zero, glitches can occur on the DLL clock output pins. Activation of the RST pin can also severely affect the duty cycle of the clock output pins. Furthermore, the DLL output clocks no longer deskew with respect to one another. The DLL must be reset when the input clock frequency changes, if the device is reconfigured in Boundary-Scan mode, if the device undergoes a hot swap, and after the device is configured if the input clock is not stable during the startup sequence.

2x Clock Output — CLK2X

The output pin CLK2X provides a frequency-doubled clock with an automatic 50/50 duty-cycle correction. Until the CLKDLL has achieved lock, the CLK2X output appears as a 1x version of the input clock with a 25/75 duty cycle. This behavior allows the DLL to lock on the correct edge with respect to source clock. This pin is not available on the CLKDLLHF primitive.

Clock Divide Output — CLKDV

The clock divide output pin CLKDV provides a lower frequency version of the source clock. The CLKDV_DIVIDE property controls CLKDV such that the source clock is divided by N where N is either 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

This feature provides automatic duty cycle correction. The CLKDV output pin has a 50/50 duty cycle for all values of the

division factor N except for non-integer division in High Frequency (HF) mode. For division factor 1.5 the duty cycle in the HF mode is 33.3% High and 66.7% Low. For division factor 2.5, the duty cycle in the HF mode is 40.0% High and 60.0% Low.

1x Clock Outputs — CLK[0/90/180/270]

The 1x clock output pin CLK0 represents a delay-compensated version of the source clock (CLKIN) signal. The CLKDLL primitive provides three phase-shifted versions of the CLK0 signal while CLKDLLHF provides only the 180 degree phase-shifted version. The relationship between phase shift and the corresponding period shift appears in Table 10.

The timing diagrams in Figure 26 illustrate the DLL clock output characteristics.

Table 10: Relationship of Phase-Shifted Output Clock to Period Shift

Phase (degrees)	Period Shift (percent)
0	0%
90	25%
180	50%
270	75%

The DLL provides duty cycle correction on all 1x clock outputs such that all 1x clock outputs by default have a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (TRUE by default), controls this feature. In order to deactivate the DLL duty cycle correction, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL primitive. When duty cycle correction deactivates, the output clock has the same duty cycle as the source clock.

The DLL clock outputs can drive an OBUF, a BUFG, or they can route directly to destination clock pins. The DLL clock outputs can only drive the BUFGs that reside on the same edge (top or bottom).

Locked Output — LOCKED

In order to achieve lock, the DLL may need to sample several thousand clock cycles. After the DLL achieves lock the LOCKED signal activates. The "DLL Timing Parameters" section of Module 3 provides estimates for locking times.

In order to guarantee that the system clock is established prior to the device "waking up," the DLL can delay the completion of the device configuration process until after the DLL locks. The STARTUP_WAIT property activates this feature.

Until the LOCKED signal activates, the DLL output clocks are not valid and can exhibit glitches, spikes, or other

spurious movement. In particular the CLK2X output will appear as a 1x clock with a 25/75 duty cycle.

DLL Properties

Properties provide access to some of the Spartan-II family DLL features, (for example, clock division and duty cycle correction).

Duty Cycle Correction Property

The 1x clock outputs, CLK0, CLK90, CLK180, and CLK270, use the duty-cycle corrected default, such that they exhibit a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (by default TRUE) controls this feature. To deactivate the DLL duty-cycle correction for the 1x clock outputs, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL primitive.



Figure 26: DLL Output Characteristics

Clock Divide Property

The CLKDV_DIVIDE property specifies how the signal on the CLKDV pin is frequency divided with respect to the CLK0 pin. The values allowed for this property are 1.5, 2, 2.5, 3, 4, 5, 8, or 16; the default value is 2. support of a wide variety of applications, from general purpose standard applications to high-speed low-voltage memory busses.

Versatile I/O blocks also provide selectable output drive strengths and programmable slew rates for the LVTTL output buffers, as well as an optional, programmable weak pull-up, weak pull-down, or weak "keeper" circuit ideal for use in external bussing applications.

Each Input/Output Block (IOB) includes three registers, one each for the input, output, and 3-state signals within the IOB. These registers are optionally configurable as either a D-type flip-flop or as a level sensitive latch.

The input buffer has an optional delay element used to guarantee a zero hold time requirement for input signals registered within the IOB.

The Versatile I/O features also provide dedicated resources for input reference voltage (V_{REF}) and output source voltage (V_{CCO}), along with a convenient banking system that simplifies board design.

By taking advantage of the built-in features and wide variety of I/O standards supported by the Versatile I/O features, system-level design and board design can be greatly simplified and improved.

Fundamentals

Modern bus applications, pioneered by the largest and most influential companies in the digital electronics industry, are commonly introduced with a new I/O standard tailored specifically to the needs of that application. The bus I/O standards provide specifications to other vendors who create products designed to interface with these applications. Each standard often has its own specifications for current, voltage, I/O buffering, and termination techniques.

The ability to provide the flexibility and time-to-market advantages of programmable logic is increasingly dependent on the capability of the programmable logic device to support an ever increasing variety of I/O standards

The Versatile I/O resources feature highly configurable input and output buffers which provide support for a wide variety of I/O standards. As shown in Table 15, each buffer type can support a variety of voltage requirements.

Table 15: Versatile I/O Supported Standards (Typical Values)

I/O Standard	Input Reference Voltage (V _{REF})	Output Source Voltage (V _{CCO})	Board Termination Voltage (V _{TT})
LVTTL (2-24 mA)	N/A	3.3	N/A
LVCMOS2	N/A	2.5	N/A
PCI (3V/5V, 33 MHz/66 MHz)	N/A	3.3	N/A
GTL	0.8	N/A	1.2
GTL+	1.0	N/A	1.5
HSTL Class I	0.75	1.5	0.75
HSTL Class III	0.9	1.5	1.5
HSTL Class IV	0.9	1.5	1.5
SSTL3 Class I and II	1.5	3.3	1.5
SSTL2 Class I and II	1.25	2.5	1.25
СТТ	1.5	3.3	1.5
AGP-2X	1.32	3.3	N/A

Overview of Supported I/O Standards

This section provides a brief overview of the I/O standards supported by all Spartan-II devices.

While most I/O standards specify a range of allowed voltages, this document records typical voltage values only. Detailed information on each specification may be found on the Electronic Industry Alliance JEDEC website at http://www.jedec.org. For more details on the I/O standards and termination application examples, see XAPP179, "Using SelectIO Interfaces in Spartan-II and Spartan-IIE FPGAs."

LVTTL — Low-Voltage TTL

The Low-Voltage TTL (LVTTL) standard is a general purpose EIA/JESDSA standard for 3.3V applications that uses an LVTTL input buffer and a Push-Pull output buffer. This standard requires a 3.3V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a termination voltage (V_{TT}).

LVCMOS2 — Low-Voltage CMOS for 2.5V

The Low-Voltage CMOS for 2.5V or lower (LVCMOS2) standard is an extension of the LVCMOS standard (JESD 8.5) used for general purpose 2.5V applications. This standard requires a 2.5V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}).

IOBUF_<slew_rate>_<drive_strength>

<slew_rate> can be either F (Fast), or S (Slow) and <drive_strength> is specified in milliamps (2, 4, 6, 8, 12, 16, or 24).





When the IOBUF primitive supports an I/O standard such as LVTTL, LVCMOS, or PCI33_5, the IBUF automatically configures as a 5V tolerant input buffer unless the V_{CCO} for the bank is less than 2V. If the single-ended IBUF is placed in a bank with an HSTL standard (V_{CCO} < 2V), the input buffer is not 5V tolerant.

The voltage reference signal is "banked" within the Spartan-II device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 36, page 39 for a representation of the Spartan-II FPGA I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input.

Additional restrictions on the Versatile I/O IOBUF placement require that within a given V_{CCO} bank each IOBUF must share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within the same V_{CCO} bank. The LOC property can specify a location for the IOBUF.

An optional delay element is associated with the input path in each IOBUF. When the IOBUF drives an input flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Override this default with the NODELAY=TRUE property.

In the case when the IOBUF does not drive an input flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

3-state output buffers and bidirectional buffers can have either a weak pull-up resistor, a weak pull-down resistor, or a weak "keeper" circuit. Control this feature by adding the appropriate primitive to the output net of the IOBUF (PULLUP, PULLDOWN, or KEEPER).

Versatile I/O Properties

Access to some of the Versatile I/O features (for example, location constraints, input delay, output drive strength, and slew rate) is available through properties associated with these features.

Input Delay Properties

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Use the NODELAY=TRUE property to override this default.

In the case when the IBUF does not drive a flip-flop within the IOB, the delay element by default de-activates to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

IOB Flip-Flop/Latch Property

The I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified:

map -pr b <filename>

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each Versatile I/O primitive with the location constraint LOC attached to the Versatile I/O primitive. The external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

LOC=A42 LOC=P37

Output Slew Rate Property

In the case of the LVTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be programmed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

SLEW=SLOW

SLEW=FAST

Output Drive Strength Property

For the LVTTL output buffers (OBUF, OBUFT, and IOBUF, the desired drive strength can be specified with the DRIVE=

SSTL3 Class I

A sample circuit illustrating a valid termination technique for SSTL3_I appears in Figure 47. DC voltage specifications appear in Table 25 for the SSTL3_I standard. See "DC Specifications" in Module 3 for the actual FPGA characteristics.

SSTL3 Class I



Figure 47: Terminated SSTL3 Class I

Table 2	25:	SSTL3_	I Voltage	Speci	fications
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Parameter	Min	Тур	Max
V _{CCO}	3.0	3.3	3.6
$V_{REF} = 0.45 \times V_{CCO}$	1.3	1.5	1.7
$V_{TT} = V_{REF}$	1.3	1.5	1.7
$V_{IH} \ge V_{REF} + 0.2$	1.5	1.7	3.9 ⁽¹⁾
$V_{IL} \leq V_{REF} - 0.2$	-0.3(2)	1.3	1.5
$V_{OH} \ge V_{REF} + 0.6$	1.9	-	-
$V_{OL} \leq V_{REF} - 0.6$	-	-	1.1
I _{OH} at V _{OH} (mA)	-8	-	-
I _{OL} at V _{OL} (mA)	8	-	-

Notes:

1. V_{IH} maximum is V_{CCO} + 0.3.

2. V_{IL} minimum does not conform to the formula.

SSTL3 Class II

A sample circuit illustrating a valid termination technique for SSTL3_II appears in Figure 48. DC voltage specifications appear in Table 26 for the SSTL3_II standard. See "DC Specifications" in Module 3 for the actual FPGA characteristics.



Figure 48: Terminated SSTL3 Class II

Table 26: SSTL3_II Voltage Specifications

Parameter	Min	Тур	Max
V _{CCO}	3.0	3.3	3.6
$V_{REF} = 0.45 \times V_{CCO}$	1.3	1.5	1.7
$V_{TT} = V_{REF}$	1.3	1.5	1.7
$V_{IH} \ge V_{REF} + 0.2$	1.5	1.7	3.9 ⁽¹⁾
$V_{IL} \leq V_{REF} - 0.2$	-0.3 ⁽²⁾	1.3	1.5
$V_{OH} \ge V_{REF} + 0.8$	2.1	-	-
$V_{OL} \leq V_{REF} - 0.8$	-	-	0.9
I _{OH} at V _{OH} (mA)	-16	-	-
I _{OL} at V _{OL} (mA)	16	-	-

Notes:

1. V_{IH} maximum is V_{CCO} + 0.3

2. V_{IL} minimum does not conform to the formula

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LVTTL

LVTTL requires no termination. DC voltage specifications appears in Table 32 for the LVTTL standard. See "DC Specifications" in Module 3 for the actual FPGA characteristics.

Table 32: LVTTL Voltage Specifications

Parameter	Min	Тур	Max
V _{CCO}	3.0	3.3	3.6
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	2.0	-	5.5
V _{IL}	-0.5	-	0.8
V _{OH}	2.4	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-24	-	-
I _{OL} at V _{OL} (mA)	24	-	-

Notes:

1. V_{OL} and V_{OH} for lower drive currents sample tested.

LVCMOS2

LVCMOS2 requires no termination. DC voltage specifications appear in Table 33 for the LVCMOS2 standard. See "DC Specifications" in Module 3 for the actual FPGA characteristics.

Table 33: LVCMOS2 Voltage Specifications

Parameter	Min	Тур	Max
V _{CCO}	2.3	2.5	2.7
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	1.7	-	5.5
V _{IL}	-0.5	-	0.7
V _{OH}	1.9	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-12	-	-
I _{OL} at V _{OL} (mA)	12	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in Table 34 for the AGP-2X standard. See "DC Specifications" in Module 3 for the actual FPGA characteristics.

Table 34: AGP-2X Voltage Specifications

Parameter	Min	Тур	Max
V _{CCO}	3.0	3.3	3.6
$V_{REF} = N \times V_{CCO}^{(1)}$	1.17	1.32	1.48
V _{TT}	-	-	-
$V_{IH} \ge V_{REF} + 0.2$	1.37	1.52	-
$V_{IL} \leq V_{REF} - 0.2$	-	1.12	1.28
$V_{OH} \ge 0.9 \times V_{CCO}$	2.7	3.0	-
$V_{OL} \le 0.1 \times V_{CCO}$	-	0.33	0.36
I _{OH} at V _{OH} (mA)	Note 2	-	-
I _{OL} at V _{OL} (mA)	Note 2	-	-

Notes:

- 1. N must be greater than or equal to 0.39 and less than or equal to 0.41.
- 2. Tested according to the relevant specification.

For design examples and more information on using the I/O, see <u>XAPP179</u>, Using SelectIO Interfaces in Spartan-II and Spartan-IIE FPGAs.

Global Clock Setup and Hold for LVTTL Standard, with DLL (Pin-to-Pin)

			Speed Grade		
			-6	-5	
Symbol	Description	Device	Min	Min	Units
T _{PSDLL} / T _{PHDLL}	Input setup and hold time relative to global clock input signal for LVTTL standard, no delay, IFF, ⁽¹⁾ with DLL	All	1.7 / 0	1.9/0	ns

Notes:

1. IFF = Input Flip-Flop or Latch

2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.

3. DLL output jitter is already included in the timing calculation.

4. A zero hold time listing indicates no hold time or a negative hold time.

 For data input with different standards, adjust the setup time delay by the values shown in "IOB Input Delay Adjustments for Different Standards," page 57. For a global clock input with standards other than LVTTL, adjust delays with values from the "I/O Standard Global Clock Input Adjustments," page 61.

Global Clock Setup and Hold for LVTTL Standard, without DLL (Pin-to-Pin)

			Speed		
			-6	-5	
Symbol	Description	Device	Min	Min	Units
T _{PSFD} / T _{PHFD}	Input setup and hold time relative	XC2S15	2.2 / 0	2.7 / 0	ns
	to global clock input signal for LVTTL standard, no delay, IFF, ⁽¹⁾ without DLL	XC2S30	2.2 / 0	2.7 / 0	ns
		XC2S50	2.2 / 0	2.7 / 0	ns
		XC2S100	2.3 / 0	2.8 / 0	ns
		XC2S150	2.4 / 0	2.9/0	ns
		XC2S200	2.4 / 0	3.0 / 0	ns

Notes:

1. IFF = Input Flip-Flop or Latch

2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.

- 3. A zero hold time listing indicates no hold time or a negative hold time.
- 4. For data input with different standards, adjust the setup time delay by the values shown in "IOB Input Delay Adjustments for Different Standards," page 57. For a global clock input with standards other than LVTTL, adjust delays with values from the "I/O Standard Global Clock Input Adjustments," page 61.

XC2S15 Device Pinouts (Continued)

XC2S15 Pad Name					Bndry
Function	Bank	VQ100	TQ144	CS144	Scan
GND	-	-	P61	J12	-
I/O (D5)	3	P57	P60	J13	245
I/O	3	P58	P59	H10	248
I/O, V _{REF}	3	P59	P58	H11	251
I/O (D4)	3	P60	P57	H12	254
I/O	3	-	P56	H13	257
V _{CCINT}	-	P61	P55	G12	-
I/O, TRDY ⁽¹⁾	3	P62	P54	G13	260
V _{CCO}	3	P63	P53	G11	-
V _{CCO}	2	P63	P53	G11	-
GND	-	P64	P52	G10	-
I/O, IRDY ⁽¹⁾	2	P65	P51	F13	263
I/O	2	-	P50	F12	266
I/O (D3)	2	P66	P49	F11	269
I/O, V _{REF}	2	P67	P48	F10	272
I/O	2	P68	P47	E13	275
I/O (D2)	2	P69	P46	E12	278
GND	-	-	P45	E11	-
I/O (D1)	2	P70	P44	E10	281
I/O	2	P71	P43	D13	284
I/O, V _{REE}	2	P72	P41	D11	287
I/O	2	-	P40	C13	290
I/O (DIN, D0)	2	P73	P39	C12	293
I/O (DOUT, BUSY)	2	P74	P38	C11	296
CCLK	2	P75	P37	B13	299
V _{CCO}	2	P76	P36	B12	-
V _{CCO}	1	P76	P35	A13	-
TDO	2	P77	P34	A12	-
GND	-	P78	P33	B11	-
TDI	-	P79	P32	A11	-
I/O (CS)	1	P80	P31	D10	0
I/O (WRITE)	1	P81	P30	C10	3
I/O	1	-	P29	B10	6
I/O, V _{REF}	1	P82	P28	A10	9
I/O	1	P83	P27	D9	12
I/O	1	P84	P26	C9	15
GND	-	-	P25	B9	-
V _{CCINT}	-	P85	P24	A9	-
I/O	1	-	P23	D8	18
I/O	1	-	P22	C8	21

XC2S15 Device Pinouts (Continued)

XC2S15 Pad Name					Bndry
Function	Bank	VQ100	TQ144	CS144	Scan
I/O, V _{REF}	1	P86	P21	B8	24
I/O	1	-	P20	A8	27
I/O	1	P87	P19	B7	30
I, GCK2	1	P88	P18	A7	36
GND	-	P89	P17	C7	-
V _{CCO}	1	P90	P16	D7	-
V _{CCO}	0	P90	P16	D7	-
I, GCK3	0	P91	P15	A6	37
V _{CCINT}	-	P92	P14	B6	-
I/O	0	-	P13	C6	44
I/O, V _{REF}	0	P93	P12	D6	47
I/O	0	-	P11	A5	50
I/O	0	-	P10	B5	53
V _{CCINT}	-	P94	P9	C5	-
GND	-	-	P8	D5	-
I/O	0	P95	P7	A4	56
I/O	0	P96	P6	B4	59
I/O, V _{REF}	0	P97	P5	C4	62
I/O	0	-	P4	A3	65
I/O	0	P98	P3	B3	68
ТСК	-	P99	P2	C3	-
V _{CCO}	0	P100	P1	A2	-
V _{CCO}	7	P100	P144	B2	-

04/18/01

Notes:

- 1. IRDY and TRDY can only be accessed when using Xilinx PCI cores.
- 2. See "VCCO Banks" for details on V_{CCO} banking.

Additional XC2S15 Package Pins

VQ100

Not Connected Pins										
P28	P29	-	-	-	-					
11/02/00										

TQ144

Not Connected Pins										
P42	P64	P78	P101	P104	P105					
P116	P138	-	-	-	-					
11/02/00		•								

CS144

00144										
Not Connected Pins										
D3	D12	J4	K13	M3	M4					
M10	N3	-	-	-	-					
11/02/00										

XC2S50 Device Pinouts

XC2S50 Pad N	Name				Bndry
Function	Bank	TQ144	PQ208	FG256	Scan
GND	-	P143	P1	GND*	-
TMS	-	P142	P2	D3	-
I/O	7	P141	P3	C2	149
I/O	7	-	-	A2	152
I/O	7	P140	P4	B1	155
I/O	7	-	-	E3	158
I/O	7	-	P5	D2	161
GND	-	-	-	GND*	-
I/O, V _{REF}	7	P139	P6	C1	164
I/O	7	-	P7	F3	167
I/O	7	-	-	E2	170
I/O	7	P138	P8	E4	173
I/O	7	P137	P9	D1	176
I/O	7	P136	P10	E1	179
GND	-	P135	P11	GND*	-
V _{CCO}	7	-	P12	V _{CCO} Bank 7*	-
V _{CCINT}	-	-	P13	V _{CCINT} *	-
I/O	7	P134	P14	F2	182
I/O	7	P133	P15	G3	185
I/O	7	-	-	F1	188
I/O	7	-	P16	F4	191
I/O	7	-	P17	F5	194
I/O	7	-	P18	G2	197
GND	-	-	P19	GND*	-
I/O, V _{REF}	7	P132	P20	H3	200
I/O	7	P131	P21	G4	203
I/O	7	-	-	H2	206
I/O	7	P130	P22	G5	209
I/O	7	-	P23	H4	212
I/O, IRDY ⁽¹⁾	7	P129	P24	G1	215
GND	-	P128	P25	GND*	-
V _{CCO}	7	P127	P26	V _{CCO} Bank 7*	-
V _{CCO}	6	P127	P26	V _{CCO} Bank 6*	-
I/O, TRDY ⁽¹⁾	6	P126	P27	J2	218
V _{CCINT}	-	P125	P28	V_{CCINT}^{*}	-
I/O	6	P124	P29	H1	224
I/O	6	-	-	J4	227
I/O	6	P123	P30	J1	230
I/O, V _{REF}	6	P122	P31	J3	233

XC2S50 Device Pinouts (Continued)

XC2S50 Pad N	lame				Bndry
Function	Bank	TQ144	PQ208	FG256	Scan
GND	-	-	P32	GND*	-
I/O	6	-	P33	K5	236
I/O	6	-	P34	K2	239
I/O	6	-	P35	K1	242
I/O	6	-	-	K3	245
I/O	6	P121	P36	L1	248
I/O	6	P120	P37	L2	251
V _{CCINT}	-	-	P38	V _{CCINT} *	-
V _{CCO}	6	-	P39	V _{CCO} Bank 6*	-
GND	-	P119	P40	GND*	-
I/O	6	P118	P41	K4	254
I/O	6	P117	P42	M1	257
I/O	6	P116	P43	L4	260
I/O	6	-	-	M2	263
I/O	6	-	P44	L3	266
I/O, V _{REF}	6	P115	P45	N1	269
GND	-	-	-	GND*	-
I/O	6	-	P46	P1	272
I/O	6	-	-	L5	275
I/O	6	P114	P47	N2	278
I/O	6	-	-	M4	281
I/O	6	P113	P48	R1	284
I/O	6	P112	P49	М3	287
M1	-	P111	P50	P2	290
GND	-	P110	P51	GND*	-
MO	-	P109	P52	N3	291
V _{CCO}	6	P108	P53	V _{CCO} Bank 6*	-
V _{CCO}	5	P107	P53	V _{CCO} Bank 5*	-
M2	-	P106	P54	R3	292
I/O	5	-	-	N5	299
I/O	5	P103	P57	T2	302
I/O	5	-	-	P5	305
I/O	5	-	P58	Т3	308
GND	-	-	-	GND*	-
I/O, V _{REF}	5	P102	P59	T4	311
I/O	5	-	P60	M6	314
I/O	5	-	-	T5	317
I/O	5	P101	P61	N6	320
I/O	5	P100	P62	R5	323

XC2S50 Device Pinouts (Continued)

XC2S50 Pad N	Name				Bndry
Function	Bank	TQ144	PQ208	FG256	Scan
I/O	3	-	-	J14	503
I/O	3	P56	P127	K15	506
V _{CCINT}	-	P55	P128	V _{CCINT} *	-
I/O, TRDY ⁽¹⁾	3	P54	P129	J15	512
V _{CCO}	3	P53	P130	V _{CCO} Bank 3*	-
V _{CCO}	2	P53	P130	V _{CCO} Bank 2*	-
GND	-	P52	P131	GND*	-
I/O, IRDY ⁽¹⁾	2	P51	P132	H16	515
I/O	2	-	P133	H14	518
I/O	2	P50	P134	H15	521
I/O	2	-	-	J13	524
I/O (D3)	2	P49	P135	G16	527
I/O, V _{REF}	2	P48	P136	H13	530
GND	-	-	P137	GND*	-
I/O	2	-	P138	G14	533
I/O	2	-	P139	G15	536
I/O	2	-	P140	G12	539
I/O	2	-	-	F16	542
I/O	2	P47	P141	G13	545
I/O (D2)	2	P46	P142	F15	548
V _{CCINT}	-	-	P143	V _{CCINT} *	-
V _{CCO}	2	-	P144	V _{CCO} Bank 2*	-
GND	-	P45	P145	GND*	-
I/O (D1)	2	P44	P146	E16	551
I/O	2	P43	P147	F14	554
I/O	2	P42	P148	D16	557
I/O	2	-	-	F12	560
I/O	2	-	P149	E15	563
I/O, V _{REF}	2	P41	P150	F13	566
GND	-	-	-	GND*	-
I/O	2	-	P151	E14	569
I/O	2	-	-	C16	572
I/O	2	P40	P152	E13	575
I/O	2	-	-	B16	578
I/O (DIN, D0)	2	P39	P153	D14	581
I/O (DOUT, BUSY)	2	P38	P154	C15	584
CCLK	2	P37	P155	D15	587
V _{CCO}	2	P36	P156	V _{CCO} Bank 2*	-

XC2S50 Device Pinouts (Continued)

XC2S50 Pad N	lame				Bndry
Function	Bank	TQ144	PQ208	FG256	Scan
V _{CCO}	1	P35	P156	V _{CCO} Bank 1*	-
TDO	2	P34	P157	B14	-
GND	-	P33	P158	GND*	-
TDI	-	P32	P159	A15	-
I/O (CS)	1	P31	P160	B13	0
I/O (WRITE)	1	P30	P161	C13	3
I/O	1	-	-	C12	6
I/O	1	P29	P162	A14	9
I/O	1	-	-	D12	12
I/O	1	-	P163	B12	15
GND	-	-	-	GND*	-
I/O, V _{REF}	1	P28	P164	C11	18
I/O	1	-	P165	A13	21
I/O	1	-	-	D11	24
I/O	1	-	P166	A12	27
I/O	1	P27	P167	E11	30
I/O	1	P26	P168	B11	33
GND	-	P25	P169	GND*	-
V _{CCO}	1	-	P170	V _{CCO} Bank 1*	-
V _{CCINT}	-	P24	P171	V _{CCINT} *	-
I/O	1	P23	P172	A11	36
I/O	1	P22	P173	C10	39
I/O	1	-	P174	B10	45
I/O	1	-	P175	D10	48
I/O	1	-	P176	A10	51
GND	-	-	P177	GND*	-
I/O, V _{REF}	1	P21	P178	B9	54
I/O	1	-	P179	E10	57
I/O	1	-	-	A9	60
I/O	1	P20	P180	D9	63
I/O	1	P19	P181	A8	66
I, GCK2	1	P18	P182	C9	72
GND	-	P17	P183	GND*	-
V _{CCO}	1	P16	P184	V _{CCO} Bank 1*	-
V _{cco}	0	P16	P184	V _{CCO} Bank 0*	-
I, GCK3	0	P15	P185	B8	73
V _{CCINT}	-	P14	P186	V_{CCINT}^{*}	-
I/O	0	P13	P187	A7	80

XC2S150 Device Pinouts (Continued)

XC2S150 Pac	d Name				Bndry
Function	Bank	PQ208	FG256	FG456	Scan
I/O	1	P174	B10	C14	72
I/O	1	-	-	B14	75
I/O	1	P175	D10	D13	81
I/O	1	P176	A10	C13	84
GND	-	P177	GND*	GND*	-
V _{cco}	1	-	V _{CCO} Bank 1*	V _{CCO} Bank 1*	-
I/O, V _{REF}	1	P178	B9	B13	87
I/O	1	P179	E10	E12	90
I/O	1	-	A9	B12	93
I/O	1	P180	D9	D12	96
I/O	1	-	-	C12	99
I/O	1	P181	A8	D11	102
I, GCK2	1	P182	C9	A11	108
GND	-	P183	GND*	GND*	-
V _{cco}	1	P184	V _{CCO} Bank 1*	V _{CCO} Bank 1*	-
V _{CCO}	0	P184	V _{CCO} Bank 0*	V _{CCO} Bank 0*	-
I, GCK3	0	P185	B8	C11	109
V _{CCINT}	-	P186	V _{CCINT} *	V _{CCINT} *	-
I/O	0	-	-	E11	116
I/O	0	P187	A7	A10	119
I/O	0	-	D8	B10	122
I/O	0	P188	A6	C10	125
I/O, V _{REF}	0	P189	B7	A9	128
V _{CCO}	0	-	V _{CCO} Bank 0*	V _{CCO} Bank 0*	-
GND	-	P190	GND*	GND*	-
I/O	0	P191	C8	B9	131
I/O	0	P192	D7	E10	134
I/O	0	-	-	D10	140
I/O	0	P193	E7	A8	143
I/O	0	-	-	D9	146
I/O	0	-	-	B8	149
I/O	0	P194	C7	E9	155
I/O	0	P195	B6	A7	158

XC2S150 Device Pinouts (Continued)

XC2S150 Pad Name					Bndry
Function	Bank	PQ208	FG256	FG456	Scan
V _{CCINT}	-	P196	V _{CCINT} *	V _{CCINT} *	-
V _{CCO}	0	P197	V _{CCO} Bank 0*	V _{CCO} Bank 0*	-
GND	-	P198	GND*	GND*	-
I/O	0	P199	A5	B7	161
I/O, V _{REF}	0	P200	C6	E8	164
I/O	0	-	-	D8	167
I/O	0	P201	B5	C7	170
I/O	0	-	D6	D7	173
I/O	0	-	-	B6	176
I/O	0	-	-	A5	179
I/O	0	P202	A4	D6	182
I/O, V _{REF}	0	P203	B4	C6	185
V _{CCO}	0	-	V _{CCO} Bank 0*	V _{CCO} Bank 0*	-
GND	-	-	GND*	GND*	-
I/O	0	P204	E6	B5	188
I/O	0	-	D5	E7	191
I/O	0	-	-	A4	194
I/O	0	-	-	E6	197
I/O	0	P205	A3	B4	200
GND	-	-	GND*	GND*	-
I/O	0	-	C5	A3	203
I/O	0	-	-	B3	206
I/O	0	-	-	D5	209
I/O	0	P206	B3	C5	212
ТСК	-	P207	C4	C4	-
V _{CCO}	0	P208	V _{CCO} Bank 0*	V _{CCO} Bank 0*	-
V _{CCO}	7	P208	V _{CCO} Bank 7*	V _{CCO} Bank 7*	-

04/18/01 Notes:

- 1. IRDY and TRDY can only be accessed when using Xilinx PCI cores.
- Pads labelled GND*, V_{CCINT}*, V_{CCO} Bank 0*, V_{CCO} Bank 1*, V_{CCO} Bank 2*, V_{CCO} Bank 3*, V_{CCO} Bank 4*, V_{CCO} Bank 5*, V_{CCO} Bank 6*, V_{CCO} Bank 7* are internally bonded to independent ground or power planes within the package.
- 3. See "VCCO Banks" for details on V_{CCO} banking.

XC2S200 Device Pinouts

XC2S200 Pad Name Bodry					
Function	Bank	PQ208	FG256	FG456	Scan
GND	-	P1	GND*	GND*	-
TMS	-	P2	D3	D3	-
I/O	7	P3	C2	B1	257
I/O	7	-	-	E4	263
I/O	7	-	-	C1	266
I/O	7	-	A2	F5	269
GND	-	-	GND*	GND*	-
I/O, V _{REF}	7	P4	B1	D2	272
I/O	7	-	-	E3	275
I/O	7	-	-	F4	281
GND	-	-	GND*	GND*	-
I/O	7	-	E3	G5	284
I/O	7	P5	D2	F3	287
GND	-	-	GND*	GND*	-
V _{CCO}	7	-	V _{CCO} Bank 7*	V _{CCO} Bank 7*	-
I/O, V _{REF}	7	P6	C1	E2	290
I/O	7	P7	F3	E1	293
I/O	7	-	-	G4	296
I/O	7	-	-	G3	299
I/O	7	-	E2	H5	302
GND	-	-	GND*	GND*	-
I/O	7	P8	E4	F2	305
I/O	7	-	-	F1	308
I/O, V _{REF}	7	P9	D1	H4	314
I/O	7	P10	E1	G1	317
GND	-	P11	GND*	GND*	-
V _{CCO}	7	P12	V _{CCO} Bank 7*	V _{CCO} Bank 7*	-
V _{CCINT}	-	P13	V _{CCINT} *	V _{CCINT} *	-
I/O	7	P14	F2	H3	320
I/O	7	P15	G3	H2	323
I/O	7	-	-	J4	326
I/O	7	-	-	H1	329
I/O	7	-	F1	J5	332
GND	-	-	GND*	GND*	-
I/O	7	P16	F4	J2	335
I/O	7	-	-	J3	338
I/O	7	-	-	J1	341
I/O	7	P17	F5	K5	344
I/O	7	P18	G2	K1	347
GND	-	P19	GND*	GND*	-

XC2S200 Device Pinouts (Continued)

XC2S200 Pad Name					Bndry
Function	Bank	PQ208	FG256	FG456	Scan
V _{CCO}	7	-	V _{CCO} Bank 7*	V _{CCO} Bank 7*	-
I/O, V _{REF}	7	P20	H3	K3	350
I/O	7	P21	G4	K4	353
I/O	7	-	-	K2	359
I/O	7	-	H2	L6	362
I/O	7	P22	G5	L1	365
I/O	7	-	-	L5	368
I/O	7	P23	H4	L4	374
I/O, IRDY ⁽¹⁾	7	P24	G1	L3	377
GND	-	P25	GND*	GND*	-
V _{CCO}	7	P26	V _{CCO} Bank 7*	V _{CCO} Bank 7*	-
V _{CCO}	6	P26	V _{CCO} Bank 6*	V _{CCO} Bank 6*	-
I/O, TRDY ⁽¹⁾	6	P27	J2	M1	380
V _{CCINT}	-	P28	V _{CCINT} *	V _{CCINT} *	-
I/O	6	-	-	M6	389
I/O	6	P29	H1	M3	392
I/O	6	-	J4	M4	395
I/O	6	-	-	N1	398
I/O	6	P30	J1	M5	404
I/O, V _{REF}	6	P31	J3	N2	407
V _{CCO}	6	-	V _{CCO} Bank 6*	V _{CCO} Bank 6*	-
GND	-	P32	GND*	GND*	-
I/O	6	P33	K5	N3	410
I/O	6	P34	K2	N4	413
I/O	6	-	-	P1	416
I/O	6	-	-	N5	419
I/O	6	P35	K1	P2	422
GND	-	-	GND*	GND*	-
I/O	6	-	K3	P4	425
I/O	6	-	-	R1	428
I/O	6	-	-	P5	431
I/O	6	P36	L1	P3	434
I/O	6	P37	L2	R2	437
V _{CCINT}	-	P38	V _{CCINT} *	V _{CCINT} *	-
V _{CCO}	6	P39	V _{CCO} Bank 6*	V _{CCO} Bank 6*	-
GND	-	P40	GND*	GND*	-
I/O	6	P41	K4	T1	440
I/O, V _{REF}	6	P42	M1	R4	443

XC2S200 Device Pinouts (Continued)

XC2S200 Pad Name					Bndry
Function	Bank	PQ208	FG256	FG456	Scan
GND	-	P198	GND*	GND*	-
I/O	0	P199	A5	B7	188
I/O, V _{REF}	0	P200	C6	E8	191
I/O	0	-	-	D8	197
I/O	0	P201	B5	C7	200
GND	-	-	GND*	GND*	-
I/O	0	-	D6	D7	203
I/O	0	-	-	B6	206
I/O	0	-	-	A5	209
I/O	0	P202	A4	D6	212
I/O, V _{REF}	0	P203	B4	C6	215
V _{CCO}	0	-	V _{CCO} Bank 0*	V _{CCO} Bank 0*	-
GND	-	-	GND*	GND*	-
I/O	0	P204	E6	B5	218
I/O	0	-	D5	E7	221
I/O	0	-	-	A4	224
I/O	0	-	-	E6	230
I/O, V _{REF}	0	P205	A3	B4	233
GND	-	-	GND*	GND*	-
I/O	0	-	C5	A3	236
I/O	0	-	-	B3	239
I/O	0	-	-	D5	242
I/O	0	P206	B3	C5	248
ТСК	-	P207	C4	C4	-
V _{cco}	0	P208	V _{CCO} Bank 0*	V _{CCO} Bank 0*	-
V _{CCO}	7	P208	V _{CCO} Bank 7*	V _{CCO} Bank 7*	-

04/18/01

- 1. IRDY and TRDY can only be accessed when using Xilinx PCI cores.
- Pads labelled GND*, V_{CCINT}*, V_{CCO} Bank 0*, V_{CCO} Bank 1*, V_{CCO} Bank 2*, V_{CCO} Bank 3*, V_{CCO} Bank 4*, V_{CCO} Bank 5*, V_{CCO} Bank 6*, V_{CCO} Bank 7* are internally bonded to independent ground or power planes within the package.
- 3. See "VCCO Banks" for details on V_{CCO} banking.

Additional XC2S200 Package Pins

PQ208

Not Connected Pins							
P55	P56	-	-	-	-		
11/02/00		•					

FG256

V _{CCINT} Pins							
C3	C14	D4	D13	E5	E12		
M5	M12	N4	N13	P3	P14		
		V _{CCO} Ba	nk 0 Pins				
E8	F8	-	-	-	-		
		V _{CCO} Ba	nk 1 Pins				
E9	F9	-	-	-	-		
		V _{CCO} Ba	nk 2 Pins				
H11	H12	-	-	-	-		
	V _{CCO} Bank 3 Pins						
J11	J12	-	-	-	-		
		V _{CCO} Ba	nk 4 Pins				
L9	M9	-	-	-	-		
	V _{CCO} Bank 5 Pins						
L8	M8	-	-	-	-		
		V _{CCO} Ba	nk 6 Pins				
J5	J6	-	-	-	-		
V _{CCO} Bank 7 Pins							
H5	H6	-	-	-	-		
GND Pins							
A1	A16	B2	B15	F6	F7		
F10	F11	G6	G7	G8	G9		
G10	G11	H7	H8	H9	H10		
J7	J8	J9	J10	K6	K7		
K8	K9	K10	K11	L6	L7		
L10	L11	R2	R15	T1	T16		
Not Connected Pins							
P4	R4	-	-	-	-		